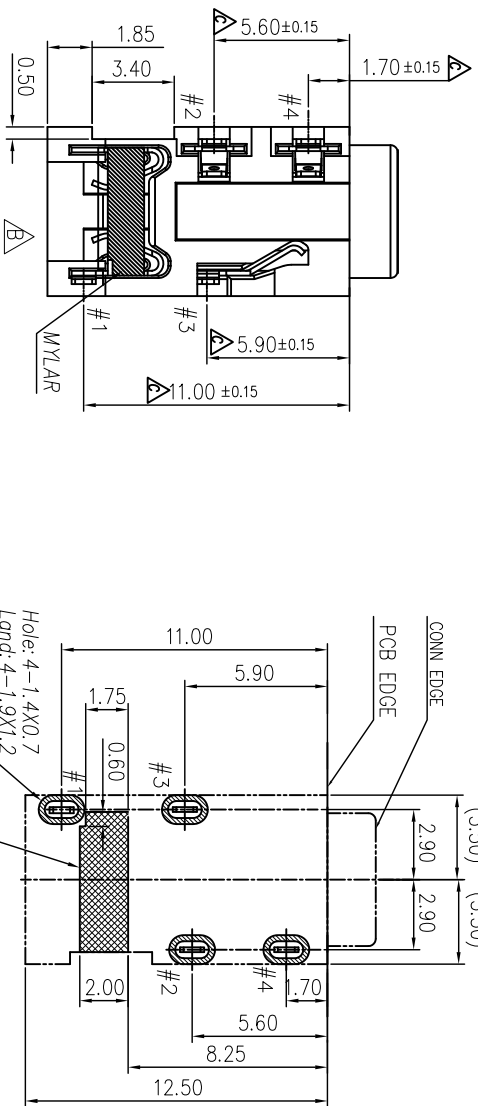
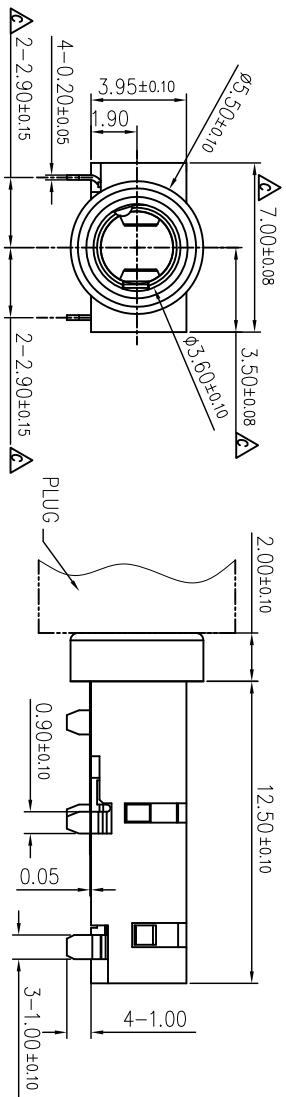
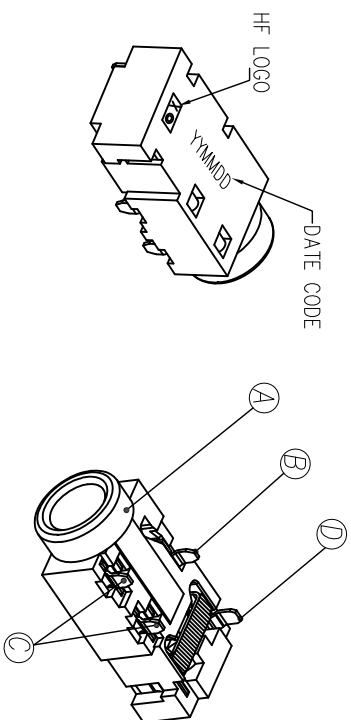
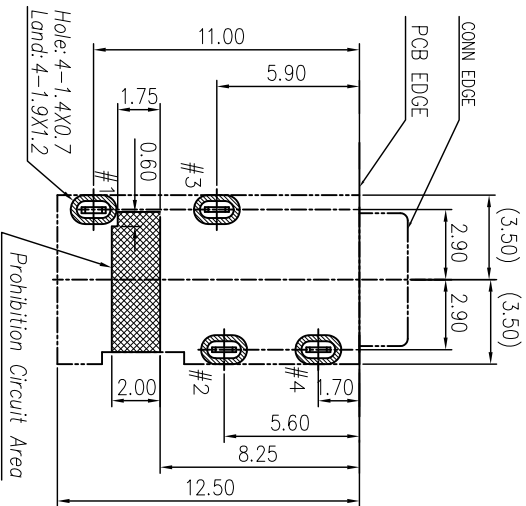


REV	ECN NO	OR DESCRIPTION	REVISED	DATE
A		PRODUCT RELEASE	Zhbin-Wei	2014.1.13
B	ECN NO.:C140034	MODIFY BODY	ZLS	2014.4.22
C	ECN NO.:C140239	MODIFY TOLERANC	REX	2014.12.08



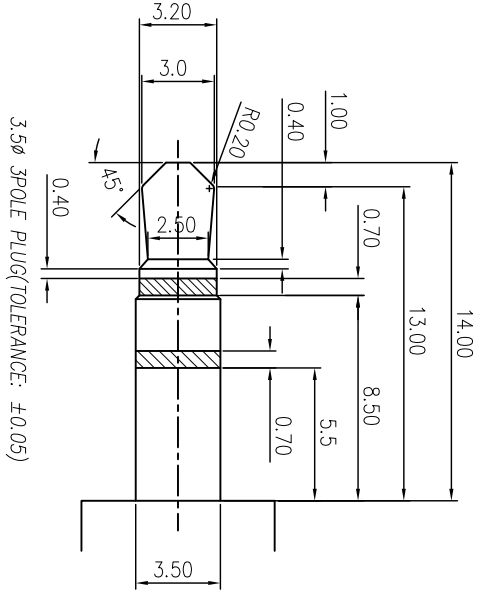
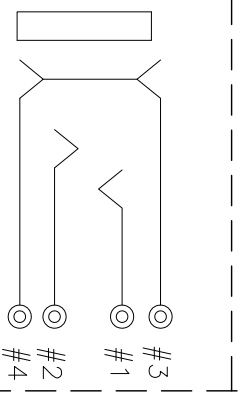
RECOMMENDED P.C.B. LAYOUT
TOP VIEW (TOLERANCE: ±0.05)



SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:
 - 1-1. RATING: 12V 1A
 - 1-2. CONTACT RESISTANCE: 30mΩ MAX.(BEFORE)
 - 1-3. DIELECTRIC VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE
 - 1-4. INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC
- MECHANICAL CHARACTERISTICS:
 - 2-1. INSERTED FORCE : 3.0 KGF MAX.
 - 2-2. WITHDRAWAL FORCE : 0.3~3.0 KGF
- LIFE TEST: 5,000 CYCLES.
- TO CONFORM TO THE SINGATRON HSF SPECIFICATION.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK:
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR IR REFLOW SOLDERING PROCESS.
- PACKAGING TAPE & REEL.

SCHEMATIC



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
E	MYLAR	1	MYLAR 0.075T	
D	TIP	1	COPPER ALLOY 0.2t	Gold Flash On Contact
C	RING A	2	COPPER ALLOY 0.2t	Area & Solder tail, All
B	EARTH	1	COPPER ALLOY 0.2t	over Nickel Plated
A	BODY	1	PA-10T+30%GF	BLACK

TITLE	DECIMALS:	ANGLES:
DWN	±0.5	X : ±2°
CHKD	±0.3	X.X : ±1°
APVD	±0.2	X.XX : ±0.2

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

3.5 PHONE JACK
PART NO. 25J2335-005111F

SCALE 4:1
UNIT: mm
SHEET: 10F1
REV: C

CUSTOMER COPY